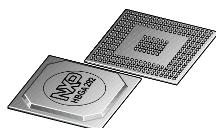


SOT553-1

plastic thermal enhanced ball grid array package; 292 balls; body 27 x 27 x 1.75 mm; heatsink

8 February 2016 — Package information

1. Package summary

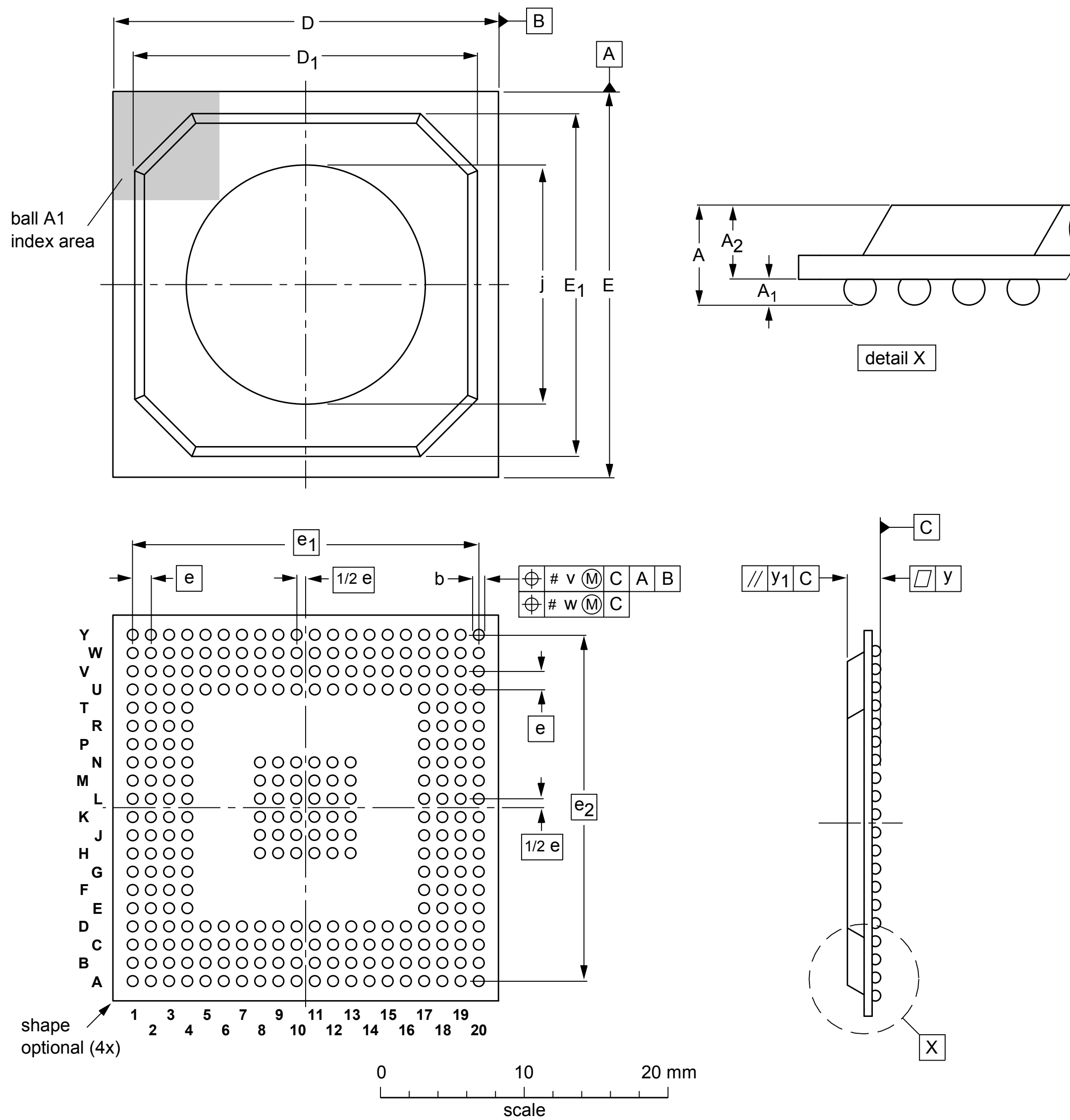
Terminal position code	B (bottom)
Package type descriptive code	HBGA292
Package type industry code	HBGA292
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	27-2-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		26.8	-	27	27.2	mm
E	package width		26.8	-	27	27.2	mm
A	seated height		[tbd]	-	2.55	2.55	mm
A_2	package height		1.6	-	1.75	1.85	mm
n_2	actual quantity of termination		-	-	292	-	

2. Package outline

HBGA292: plastic thermal enhanced ball grid array package; 292 balls; body 27 x 27 x 1.75 mm; heatsink **SOT553-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	b	D	D_1	E	E_1	e	e_1	e_2	j	v	w	y	y_1
mm	2.55	0.7 0.5	1.85 1.60	0.9 0.6	27.2 26.8	24.75 23.75	27.2 26.8	24.75 23.75	1.27	24.13	24.13	22 18	0.3	0.15	0.15	0.35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT553-1	144E	MS-034	- - -			~~00-03-04~~ 02-02-27

Fig. 1. Package outline HBGA292 (SOT553-1)

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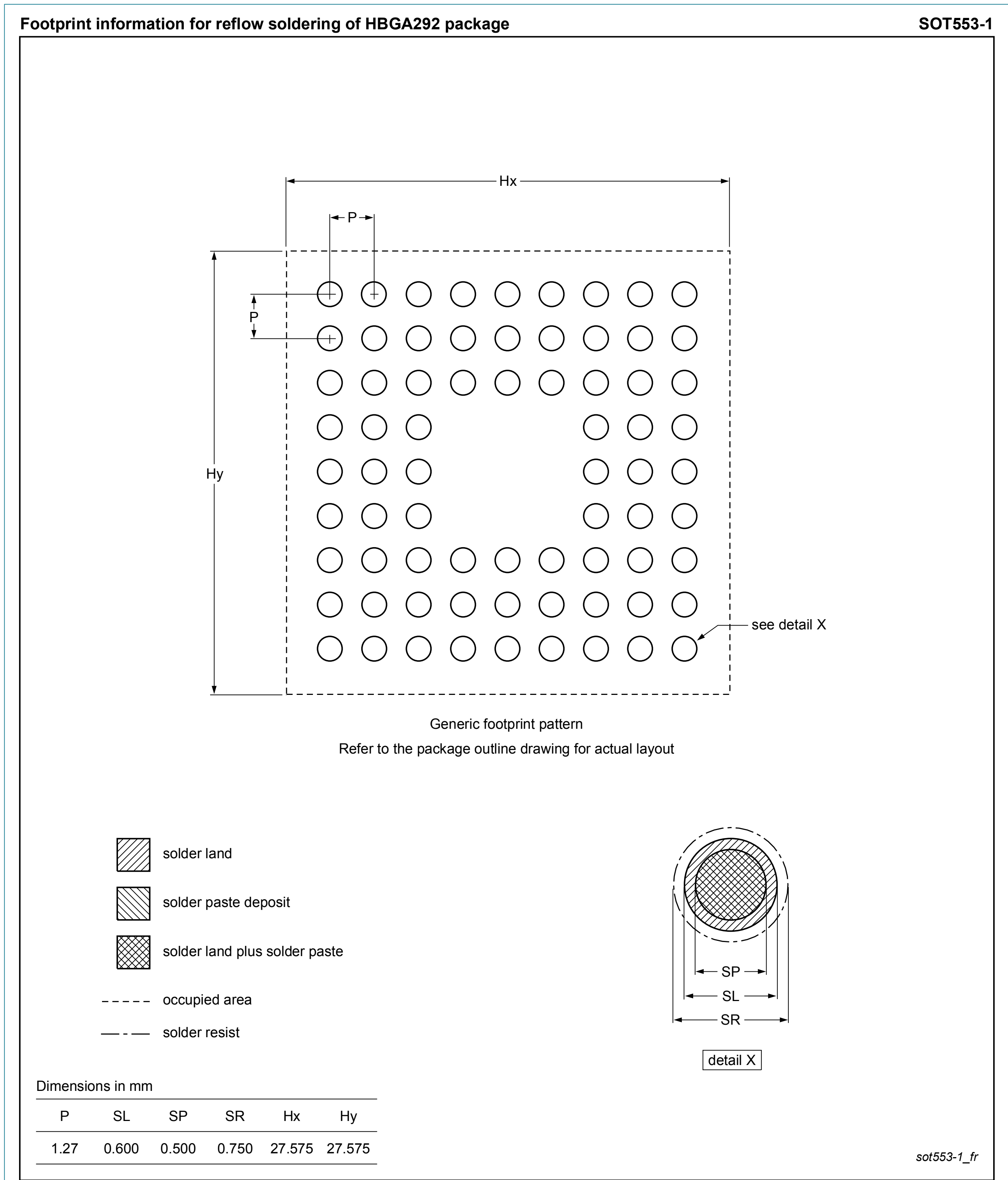
3. Soldering



P	SL	SP	SR	Hx	Hy
1.27	0.600	0.500	0.750	27.575	27.575

Fig. 2. Reflow soldering footprint for HBGA292 (SOT553-1)

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